

the semiconductor element is separable] which is detachable from the substrate.

2. (Amended) The semiconductor device according to claim 1, which [is separable] can be separated into (a) a laminate [having] including the semiconductor element [,] and (b) the substrate.

Q1  
B3  
3. (Amended) The semiconductor device according to claim 1, [which] further [comprises] comprising a protective layer, and [is separable] can be separated into (a) a laminate [having] including the semiconductor element [,] and (b) the protective layer.

Q2  
6. (Amended) The semiconductor device according to claim 5, wherein the thermoplastic resin is [of] a non-crosslinking thermoplastic resin.

B4  
Q3  
25. (Amended) A solar cell module comprising a substrate, a filler, a photovoltaic element which is detachable from the substrate, and a protective layer [, wherein the photovoltaic element is separable from the substrate].

13  
12  
26. (Amended) The solar cell module according to claim 25, which [is separable] can be separated into (a) a laminate [having] including the photovoltaic element [,] and (b) the substrate.

14.

21. (Amended) The solar cell module according to claim <sup>12</sup>~~25~~, which [is separable] can be separated into (a) a laminate [having] including the photovoltaic element [,] and (b) the protective layer.

a3

30. (Amended) The solar cell module according to

claim 29, wherein the thermoplastic resin is [of] a non-crosslinking thermoplastic resin.

a4

49. (Amended) A semiconductor device comprising a

substrate, a filler and a semiconductor element, wherein at least one of the substrate, the filler and the semiconductor element [is separable] can be detached from the other constituent members by [heating] heating the semiconductor device.

50. (Amended) A semiconductor device comprising a

substrate, a filler and a semiconductor element, wherein at least one of the substrate, the filler and the semiconductor element [is separable] can be detached from the other constituent members by heating and moistening the semiconductor device.

a5

51. (Amended) A semiconductor device comprising a

substrate, a filler and a semiconductor element, wherein at least one of the substrate, the filler and the semiconductor element [is separable] can be detached from the other

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constituent members by irradiating the semiconductor device with electron rays.

52. (Amended) A semiconductor device comprising a substrate, a filler and a semiconductor element, wherein at least one of the substrate, the filler and the semiconductor element [is separable] can be detached from the other constituent members by immersing the semiconductor device in a liquid.

05 53. (Amended) A solar cell module comprising a substrate, a filler, a photovoltaic element and a protective layer, wherein at least one of the substrate, the filler, the photovoltaic element and the protective layer [is separable] can be detached from the other constituent members by heating the solar cell module.

54. (Amended) A solar cell module comprising a substrate, a filler, a photovoltaic element and a protective layer, wherein at least one of the substrate, the filler, the photovoltaic element and the protective layer [is separable] can be detached from the other constituent members by heating and moistening the solar cell module.

Sub C117 55. (Amended) A solar cell module comprising a substrate, a filler, a photovoltaic element and a protective layer, wherein at least one of the substrate, the filler, the